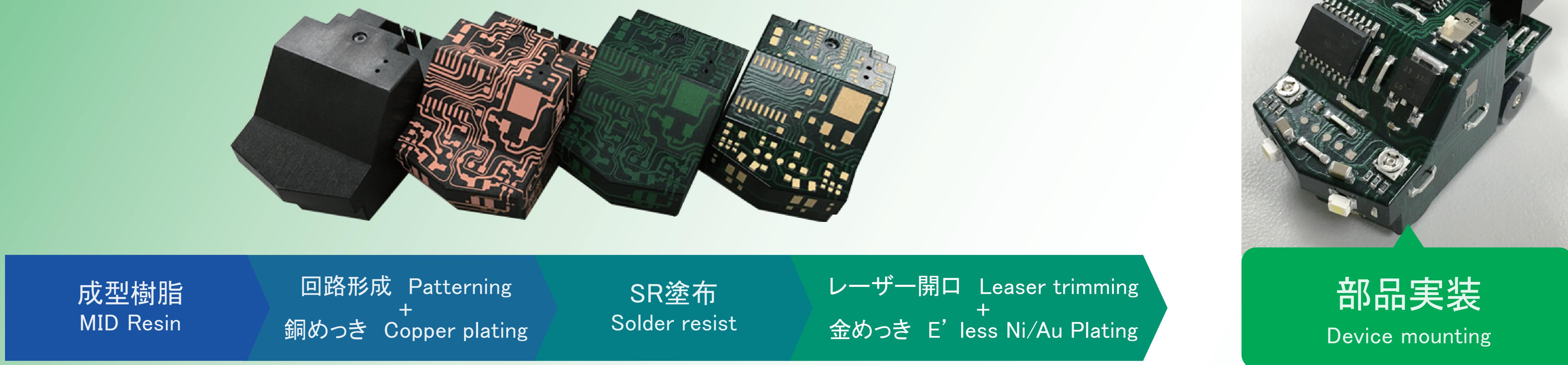




立体成型基板用ソルダーレジスト

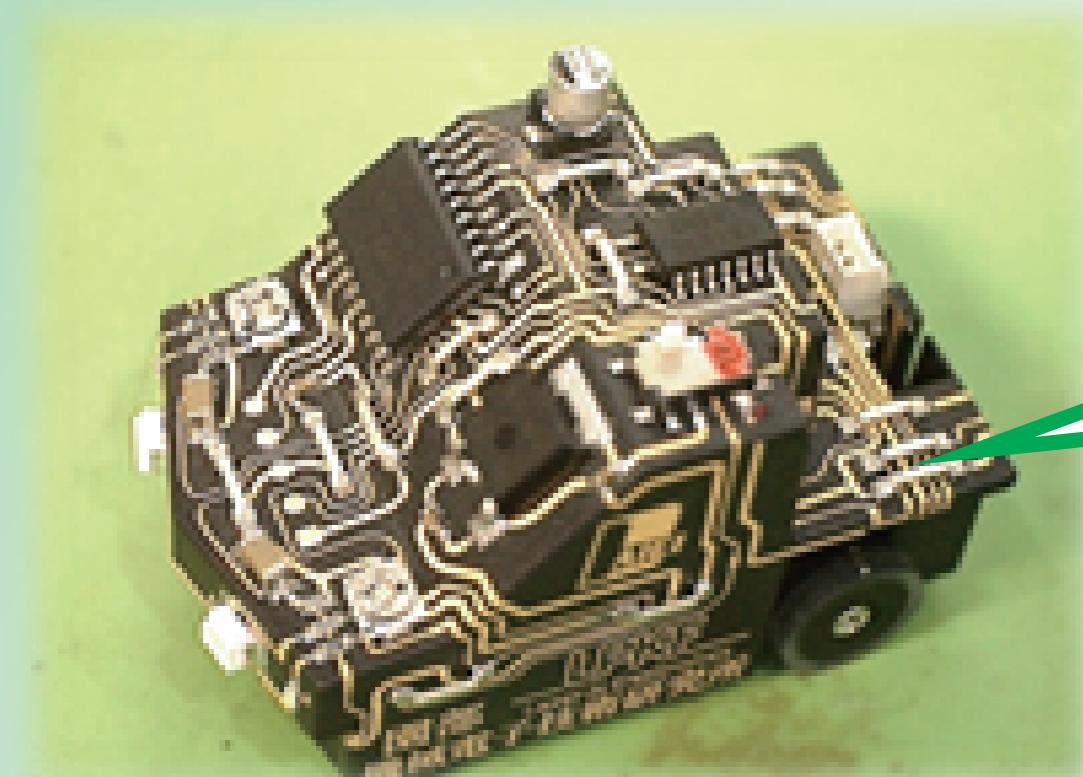
3D-MID用ソルダーレジスト

● 3D-MID基板の作成方法 Process flow of 3D-MID

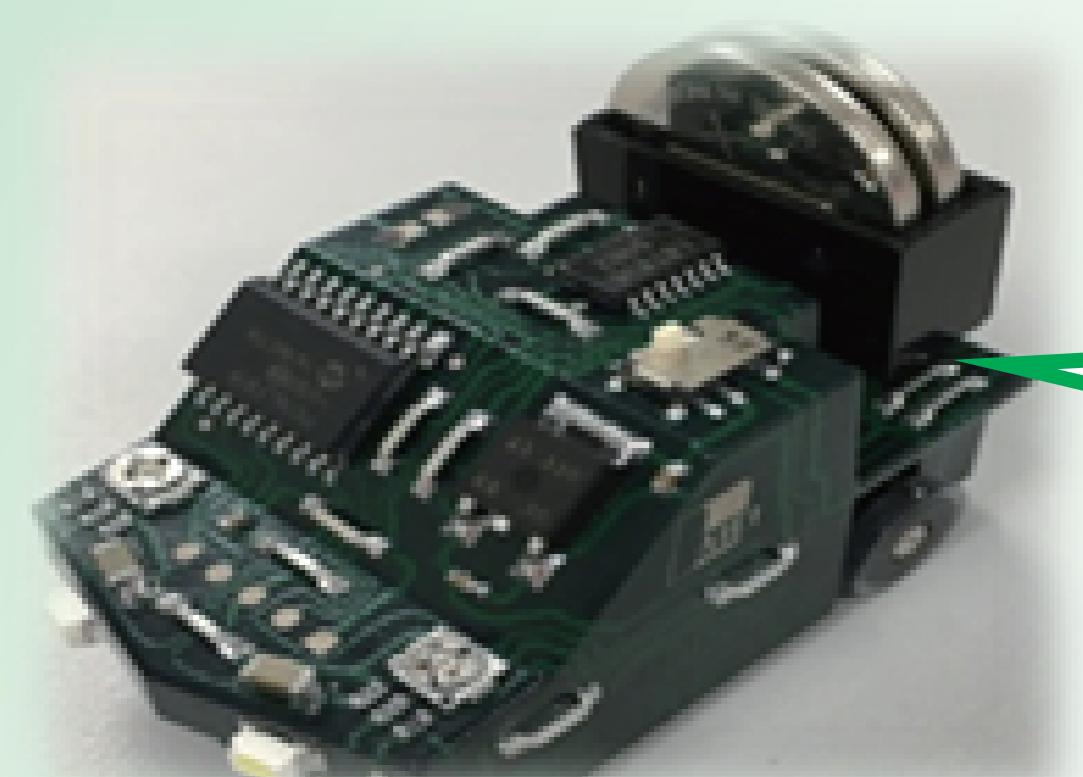


● ソルダーレジストの目的 Roles of Solder resist

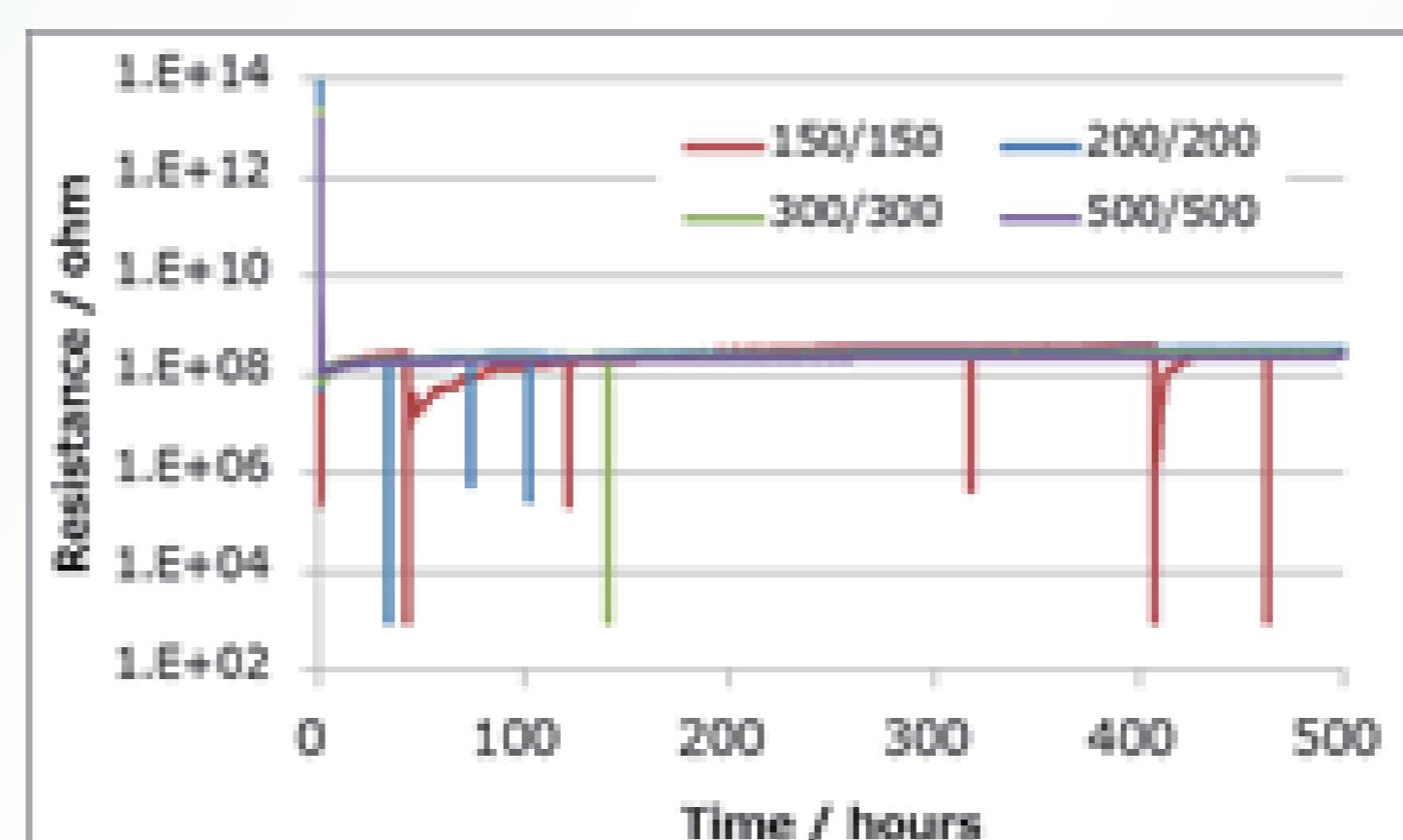
実装時の流れ防止
Prevention of solder outflow



金めっき削減によるコストダウン
Cost reduction by reducing gold plating area

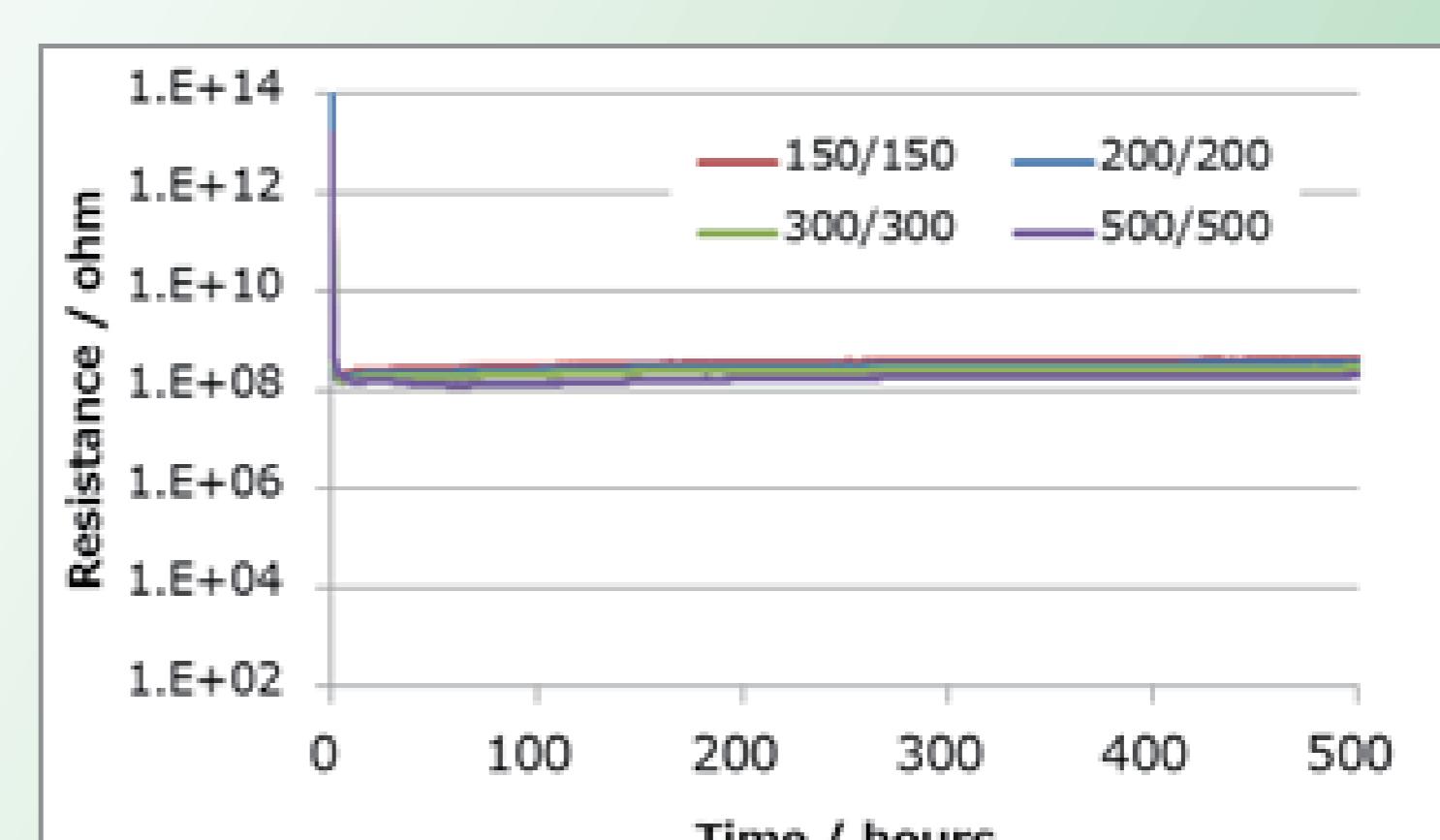


高絶縁信頼性
High insulation reliability

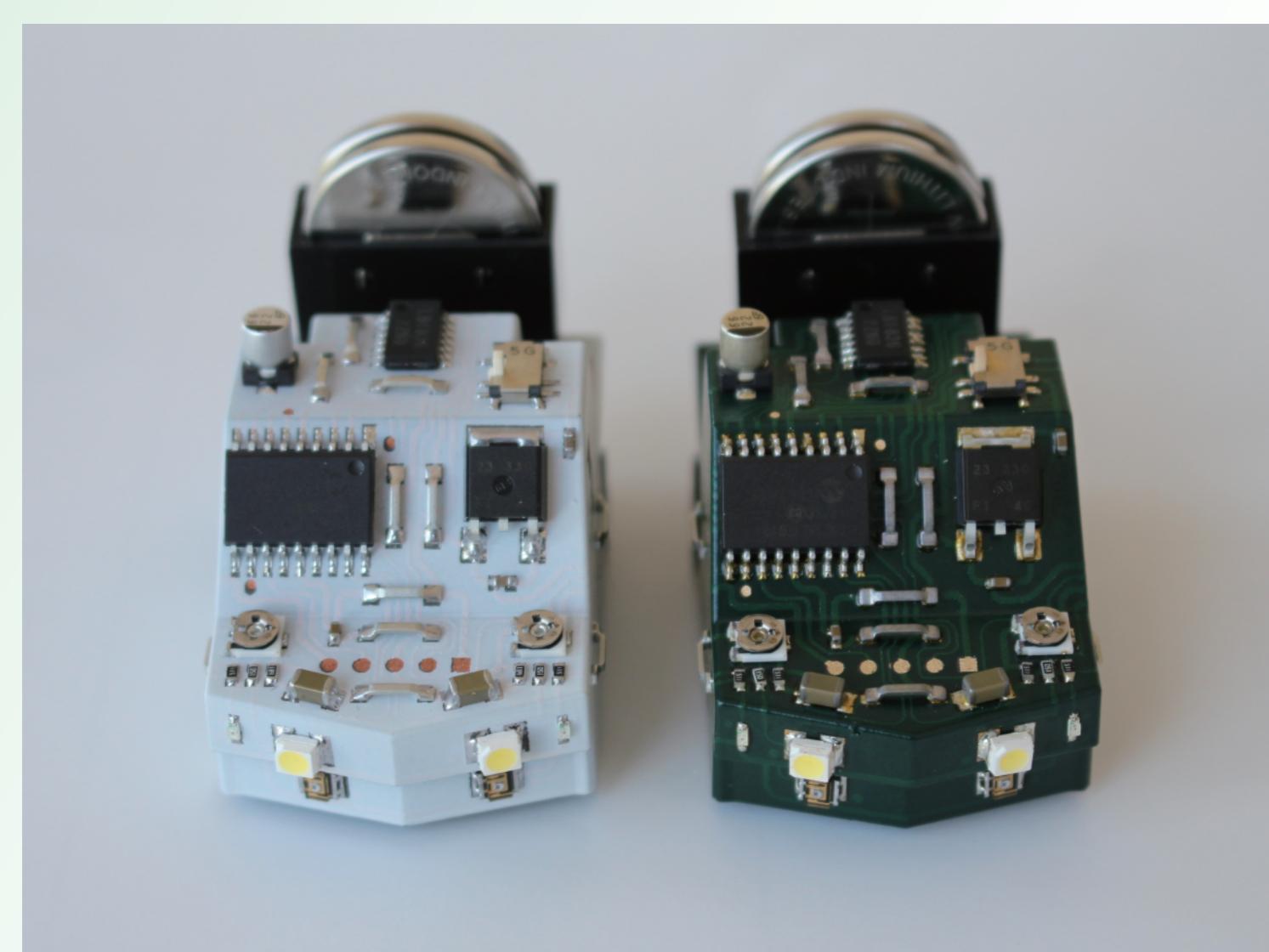


電気特性(85deg.C/85%RH/DC30V 基材:PA)
L/S=150/150, 200/200, 300/300, 500/500 um

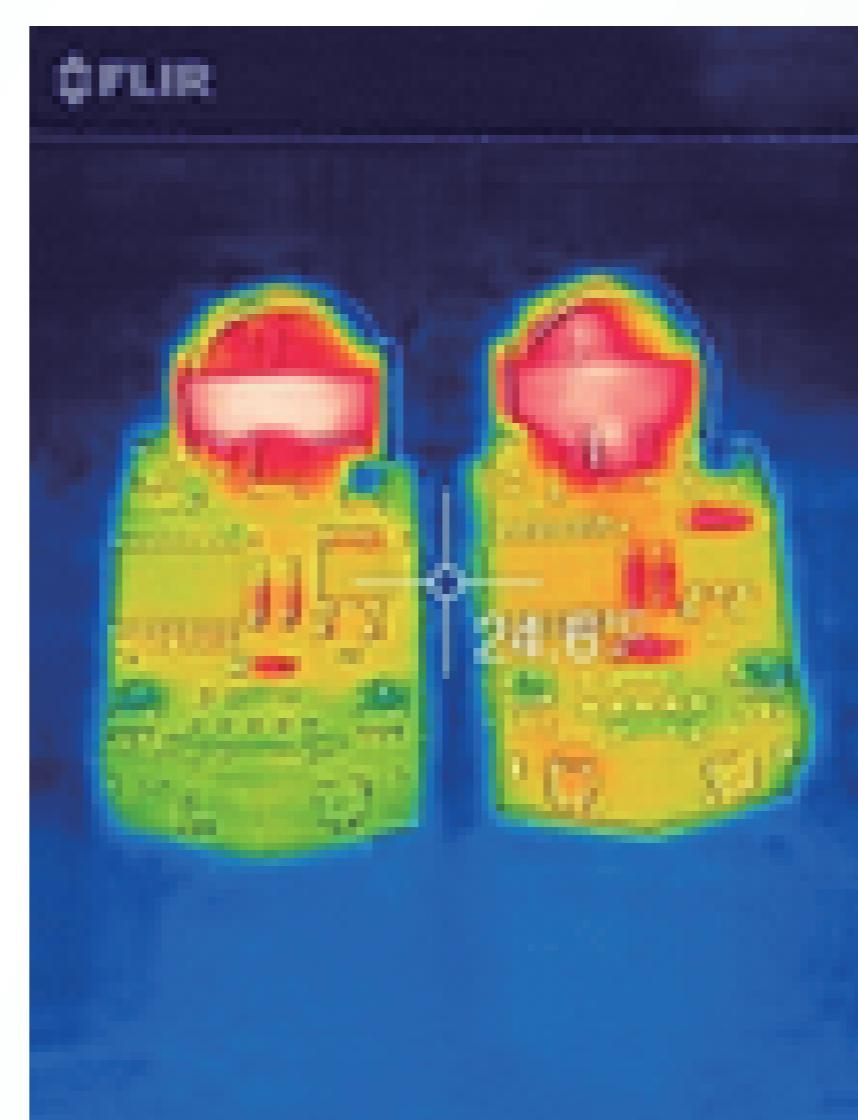
ソルダーレジストがあれば



● 放熱性向上対応等各種ソルダーレジストの使用が可能 Solder-resist depending on purpose is available



高放熱ソルダーレジスト塗布
High insulation reliability



Actual temperature
by thermo graph